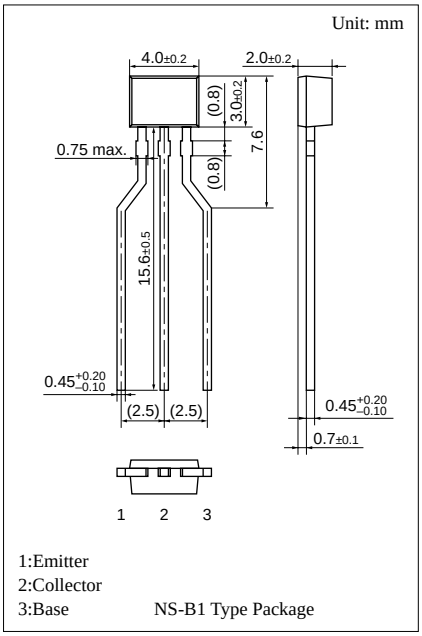
2SA1323

Silicon PNP epitaxial planer type

For high-frequency amplification
Complementary to 2SC3314



Features

- Allowing supply with the radial taping.
- High transition frequency f_T.
- Optimum for high-density mounting.

Absolute Maximum Ratings (Ta=25˚C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	–30	V
Collector to emitter voltage	V_{CEO}	–20	V
Emitter to base voltage	V_{EBO}	–5	V
Peak collector current	I_{CP}	–60	mA
Collector current	I_C	–30	mA
Collector power dissipation	P_C	300	mW
Junction temperature	T_j	150	˚C
Storage temperature	T_{stg}	–55 ~ +150	˚C

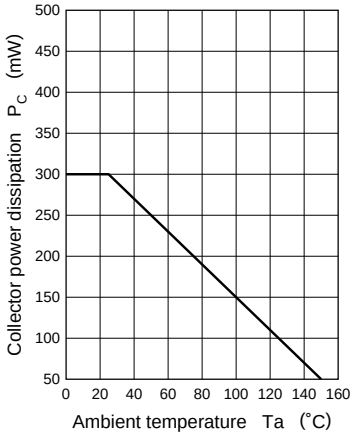
Electrical Characteristics (Ta=25˚C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	V_{CB} = –10V, I_E = 0			– 0.1	μA
	I_{CEO}	V_{CE} = –20V, I_B = 0			–100	μA
Emitter cutoff current	I_{EBO}	V_{EB} = –5V, I_C = 0			–10	μA
Forward current transfer ratio	h_{FE}*	V_{CE} = –10V, I_C = –1mA	70		220	
Collector to emitter saturation voltage	$V_{CE(sat)}$	I_C = –10mA, I_B = –1mA		– 0.1		V
Base to emitter voltage	V_{BE}	V_{CE} = –10V, I_C = –1mA		– 0.7		V
Transition frequency	f_T	V_{CB} = –10V, I_E = 1mA, f = 200MHz	150	300		MHz
Noise figure	NF	V_{CB} = –10V, I_E = 1mA, f = 5MHz		2.8	4.0	dB
Reverse transfer impedance	Z_{rb}	V_{CB} = –10V, I_E = 1mA, f = 2MHz		22	50	Ω
Common emitter reverse transfer capacitanse	C_{re}	V_{CE} = –10V, I_C = –1mA, f = 10.7MHz		1.2	2.0	pF

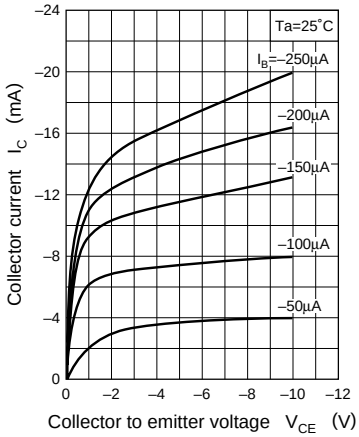
*h_{FE} Rank classification

Rank	B	C
h_{FE}	70 ~ 140	110 ~ 220

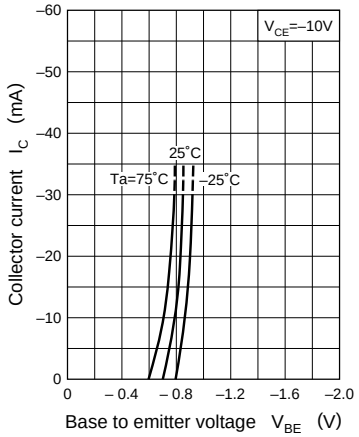
P_C — Ta



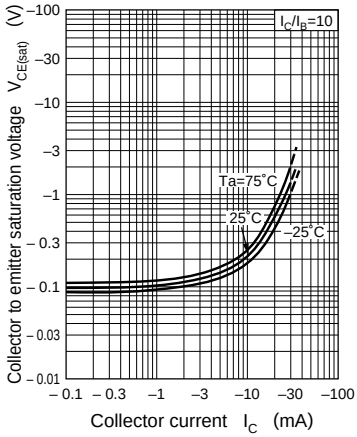
I_C — V_{CE}



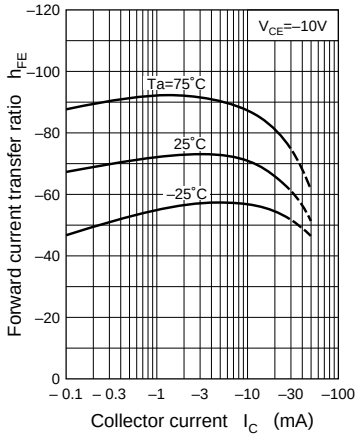
I_C — V_{BE}



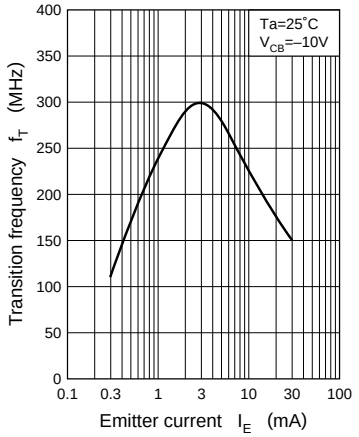
$V_{CE(sat)}$ — I_C



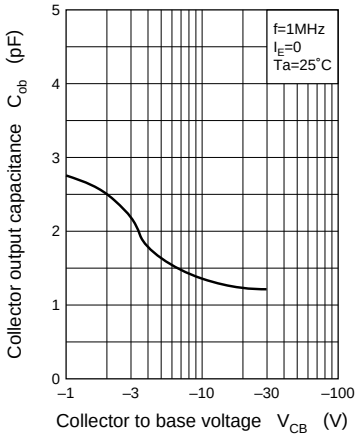
h_{FE} — I_C



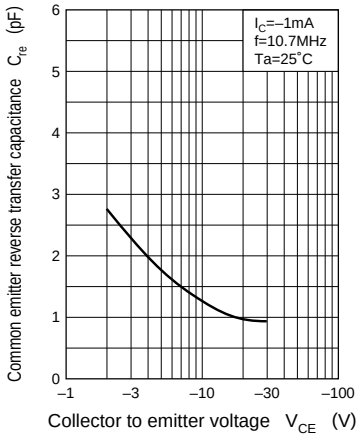
f_T — I_E



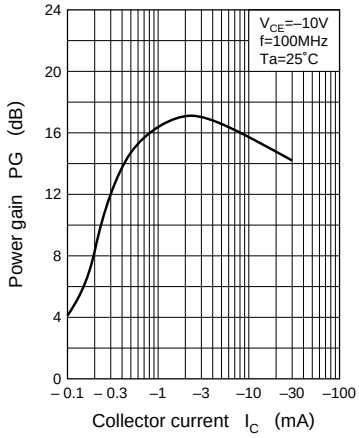
C_{ob} — V_{CB}



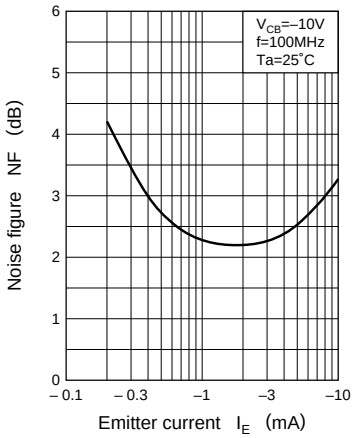
C_{re} — V_{CE}



PG — I_C



NF — I_E


V_{CB}=–10V
f=100MHz
Ta=25°C
Noise figure NF (dB)
0
1
2
3
4
5
6
– 0.1
– 0.3
–1
–3
–10
Emitter current I_E (mA)

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